

8-Bit Serial or Parallel - Input/Serial-Output Shift Register with Input Latch

High-Performance Silicon-Gate CMOS

MC74HC597A

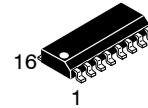
The MC74HC597A is identical in pinout to the LS597. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

This device consists of an 8-bit input latch which feeds parallel data to an 8-bit shift register. Data can also be loaded serially.

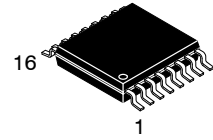
The HC597A is similar in function to the HC589A, which is a 3-state device.

Features

- Output Drive Capability: 10 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2.0 to 6.0 V
- Low Input Current: 1.0 μ A
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance with the Requirements Defined by JEDEC Standard No. 7A
- Chip Complexity: 516 FETs or 129 Equivalent Gates
- These are Pb-Free Devices*



SOIC-16
D SUFFIX
CASE 751B

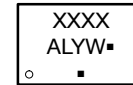
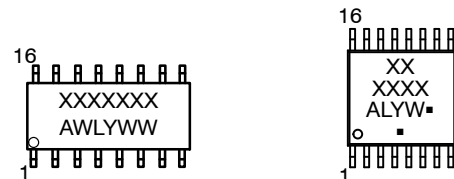


TSSOP-16
DT SUFFIX
CASE 948F



QFN16
MN SUFFIX
CASE 485AW

MARKING DIAGRAMS



A = Assembly Location
 WL, L = Wafer Lot
 YY, Y = Year
 WW, W = Work Week
 G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information on page 11 of this data sheet.

*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MC74HC597A

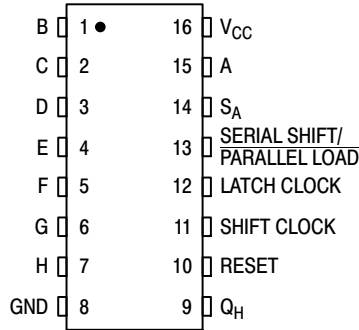


Figure 1. Pin Assignment

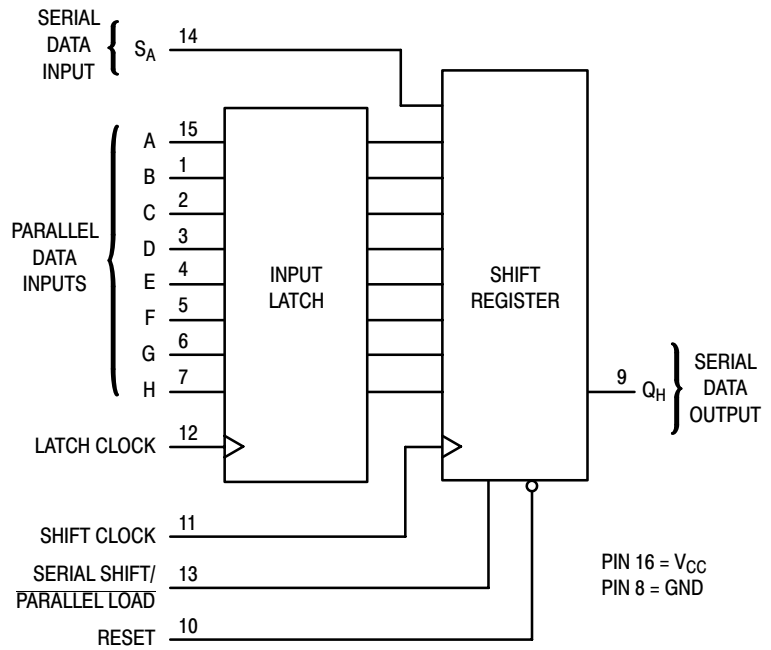


Figure 2. Logic Diagram

FUNCTION TABLE

Operation	Inputs						Resulting Function		
	Re-set	Serial Shift/ Parallel Load	Latch Clock	Shift Clock	Serial Input S _A	Parallel Inputs A-H	Latch Contents	Shift Register Contents	Output Q _H
Reset shift register	L	X	L, H, $\bar{\text{L}}$	X	X	X	U	L	L
Reset shift register; load parallel data into data latch	L	X	$\bar{\text{L}}$	X	X	a-h	a-h	L	L
Load parallel data into data latch	H	H	$\bar{\text{L}}$	L, H, $\bar{\text{L}}$	X	a-h	a-h	U	U
Transfer latch contents to shift register	H	L	L, H, $\bar{\text{L}}$	X	X	X	U	LR _N → SR _N	LR _H
Contents of data latch and shift register are unchanged	H	H	L, H, $\bar{\text{L}}$	L, H, $\bar{\text{L}}$	X	X	U	U	U
Load parallel data into data latch and shift register	H	L	$\bar{\text{L}}$	X	X	a-h	a-h	a-h	h
Shift serial data into shift register	H	H	X	$\bar{\text{L}}$	D	X	*	SR _A = D; SR _N → SR _{N+1}	SR _G → SR _H
Load parallel data into data latch and shift serial data in- to shift register	H	H	$\bar{\text{L}}$	$\bar{\text{L}}$	D	a-h	a-h	SR _A = D; SR _N → SR _{N+1}	SR _G → SR _H

LR = latch register contents
SR = shift register contents
* = depends on latch clock input

a-h = data at parallel data inputs A-H
D = data (L, H) at serial data input S_A

U = remains unchanged
X = don't care

MC74HC597A

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage	−0.5 to +6.5	V
V_{IN}	DC Input Voltage	−0.5 to $V_{CC} + 0.5$	V
V_{OUT}	DC Output Voltage	−0.5 to $V_{CC} + 0.5$	V
I_{IN}	DC Input Current, per Pin	±20	mA
I_{OUT}	DC Output Current, per Pin	±25	mA
I_{CC}	DC Supply Current, V_{CC} and GND Pins	±50	mA
I_{IK}	Input Clamp Current ($V_{IN} < 0$ or $V_{IN} > V_{CC}$)	±20	mA
I_{OK}	Output Clamp Current ($V_{OUT} < 0$ or $V_{OUT} > V_{CC}$)	±20	mA
T_{STG}	Storage Temperature	−65 to +150	°C
T_L	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
T_J	Junction Temperature Under Bias	±150	°C
θ_{JA}	Thermal Resistance (Note 1)	SOIC-16 QFN16 TSSOP-16	126 118 159 °C/W
P_D	Power Dissipation in Still Air at 25°C	SOIC-16 QFN16 TSSOP-16	995 1062 787 mW
MSL	Moisture Sensitivity	Level 1	–
F_R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in
V_{ESD}	ESD Withstand Voltage (Note 2)	Human Body Model Charged Device Model	2000 N/A V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Measured with minimum pad spacing on an FR4 board, using 76 mm-by-114 mm, 2-ounce copper trace no air flow per JESD51-7.
2. HBM tested to EIA / JESD22-A114-A. CDM tested to JESD22-C101-A. JEDEC recommends that ESD qualification to EIA/JESD22-A115A (Machine Model) be discontinued.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	2.0	6.0	V
V_{in}, V_{out}	DC Input Voltage, Output Voltage (Referenced to GND)	0	V_{CC}	V
T_A	Operating Temperature, All Package Types	−55	+125	°C
t_r, t_f	Input Rise and Fall Time	$V_{CC} = 2.0\text{ V}$ $V_{CC} = 3.0\text{ V}$ $V_{CC} = 4.5\text{ V}$ $V_{CC} = 6.0\text{ V}$	0 0 0 0	1000 600 500 400 ns

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

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DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test Conditions	V _{CC} V	Guaranteed Limit			Unit
				–55 to 25°C	≤ 85°C	≤ 125°C	
V _{IH}	Minimum High-Level Input Voltage	V _{out} = 0.1 V or V _{CC} – 0.1 V I _{out} ≤ 20 µA	2.0 3.0 4.5 6.0	1.5 2.1 3.15 4.2	1.5 2.1 3.15 4.2	1.5 2.1 3.15 4.2	V
V _{IL}	Maximum Low-Level Input Voltage	V _{out} = 0.1 V or V _{CC} – 0.1 V I _{out} ≤ 20 µA	2.0 3.0 4.5 6.0	0.5 0.9 1.35 1.8	0.5 0.9 1.35 1.8	0.5 0.9 1.35 1.8	V
V _{OH}	Minimum High-Level Output Voltage	V _{in} = V _{IH} or V _{IL} I _{out} ≤ 20 µA	2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	V
		V _{in} = V _{IH} or V _{IL} I _{out} ≤ 2.4 mA I _{out} ≤ 4.0 mA I _{out} ≤ 5.2 mA	3.0 4.5 6.0	2.48 3.98 5.48	2.34 3.84 5.34	2.20 3.70 5.20	
V _{OL}	Maximum Low-Level Output Voltage	V _{in} = V _{IH} or V _{IL} I _{out} ≤ 20 µA	2.0 4.5 6.0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V
		V _{in} = V _{IH} or V _{IL} I _{out} ≤ 2.4 mA I _{out} ≤ 4.0 mA I _{out} ≤ 5.2 mA	3.0 4.5 6.0	0.26 0.26 0.26	0.33 0.33 0.33	0.40 0.40 0.40	
I _{in}	Maximum Input Leakage Current	V _{in} = V _{CC} or GND	6.0	±0.1	±1.0	±1.0	µA
I _{CC}	Maximum Quiescent Supply Current (per Package)	V _{in} = V _{CC} or GND I _{out} = 0 µA	6.0	4	40	160	µA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

MC74HC597A

AC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	V _{CC} V	Guaranteed Limit			Unit
			–55 to 25° C	≤ 85° C	≤ 125° C	
f _{max}	Maximum Clock Frequency (50% Duty Cycle), Shift Clock (Figures 3 and 5)	2.0	10	9	8	MHz
		3.0	15	14	12	
		4.5	30	28	25	
		6.0	50	45	40	
t _{PLH} , t _{PHL}	Maximum Propagation Delay, Latch Clock to Q _H (Figures 3 and 4)	2.0	175	225	275	ns
		3.0	100	110	125	
		4.5	40	50	60	
		6.0	30	40	50	
t _{PLH} , t _{PHL}	Maximum Propagation Delay, Shift Clock to Q _H (Figures 3 and 5)	2.0	160	200	240	ns
		3.0	90	130	160	
		4.5	30	40	48	
		6.0	25	30	40	
t _{PHL}	Maximum Propagation Delay, Reset to Q _H (Figures 3 and 6)	2.0	160	200	240	ns
		3.0	90	130	160	
		4.5	30	40	48	
		6.0	25	30	40	
t _{PLH} , t _{PHL}	Maximum Propagation Delay, Serial Shift/Parallel Load to Q _H (Figures 3 and 7)	2.0	160	200	240	ns
		3.0	90	130	160	
		4.5	30	40	48	
		6.0	25	30	40	
t _{TLH} , t _{THL}	Maximum Output Transition Time, Any Output (Figures 3 and 4)	2.0	75	95	110	ns
		3.0	27	32	36	
		4.5	15	19	22	
		6.0	13	16	19	
C _{in}	Maximum Input Capacitance	–	10	10	10	pF

C _{PD}	Power Dissipation Capacitance (Per Package)*	Typical @ 25° C, V _{CC} = 5.0 V	pF
		40	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

*Used to determine the no-load dynamic power consumption: $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$.

MC74HC597A

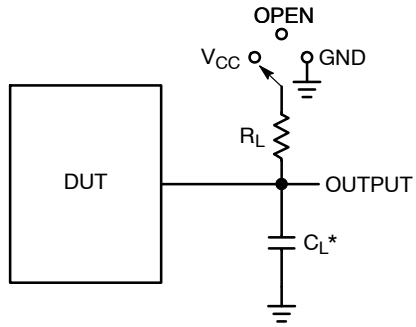
TIMING REQUIREMENTS

Symbol	Parameter	V _{CC} V	Guaranteed Limit			Unit
			-55 to 25°C	≤ 85°C	≤ 125°C	
t _{su}	Minimum Setup Time, Parallel Data inputs A–H to Latch Clock (Figure 8)	2.0	70	80	90	ns
		3.0	40	45	50	
		4.5	15	19	24	
		6.0	13	16	20	
t _{su}	Minimum Setup Time, Serial Data Input S _A to Shift Clock (Figure 9)	2.0	70	80	90	ns
		3.0	40	45	50	
		4.5	15	19	24	
		6.0	13	16	20	
t _{su}	Minimum Setup Time, Serial Shift/Parallel Load to Shift Clock (Figure 10)	2.0	70	80	90	ns
		3.0	40	45	50	
		4.5	15	19	24	
		6.0	13	16	20	
t _h	Minimum Hold Time, Latch Clock to Parallel Data Inputs A–H (Figure 8)	2.0	15	20	30	ns
		3.0	10	15	25	
		4.5	2	3	5	
		6.0	2	3	4	
t _h	Minimum Hold Time, Shift Clock to Serial Data Input S _A (Figure 9)	2.0	2	2	2	ns
		3.0	2	2	2	
		4.5	2	2	2	
		6.0	2	2	2	
t _{rec}	Minimum Recovery Time, Reset Inactive to Shift Clock (Figure 6)	2.0	70	80	90	ns
		3.0	40	45	50	
		4.5	15	19	24	
		6.0	13	16	20	
t _w	Minimum Pulse Width, Latch Clock and Shift Clock (Figures 4 and 5)	2.0	60	70	80	ns
		3.0	35	40	45	
		4.5	12	15	19	
		6.0	10	13	16	
t _w	Minimum Pulse Width, Reset (Figure 6)	2.0	60	70	80	ns
		3.0	35	40	45	
		4.5	12	15	19	
		6.0	10	13	16	
t _w	Minimum Pulse Width, Serial Shift/Parallel Load (Figure 7)	2.0	60	70	80	ns
		3.0	35	40	45	
		4.5	12	15	19	
		6.0	10	13	16	
t _r , t _f	Maximum Input Rise and Fall Times (Figure 4)	2.0	1000	1000	1000	ns
		3.0	800	800	800	
		4.5	500	500	500	
		6.0	400	400	400	

*Information on typical parametric values can be found in Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

MC74HC597A

SWITCHING WAVEFORMS



*C_L Includes probe and jig capacitance

Test	Switch Position	C _L	R _L
t _{PLH} / t _{PHL}	Open	50 pF	1 kΩ
t _{PLZ} / t _{PZL}	V _{CC}		
t _{PHZ} / t _{PZH}	GND		

Figure 3. Test Circuit

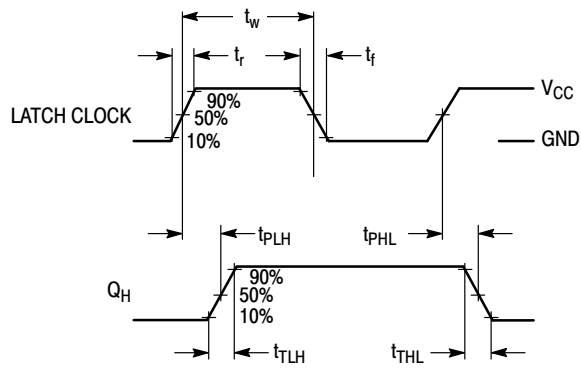


Figure 4. (Serial Shift/Parallel Load = L)

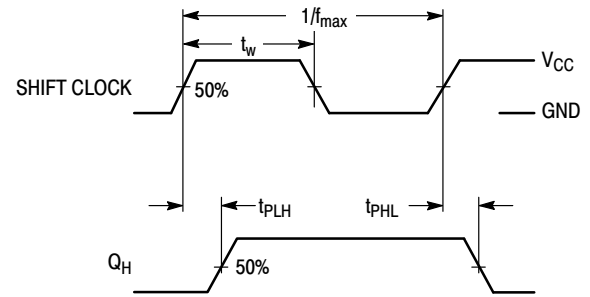


Figure 5. (Serial Shift/Parallel Load = H)

MC74HC597A

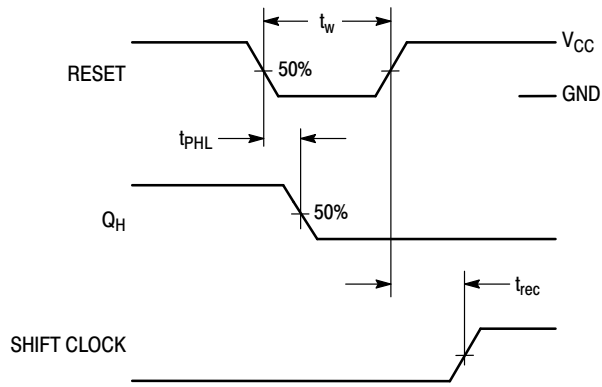


Figure 6.

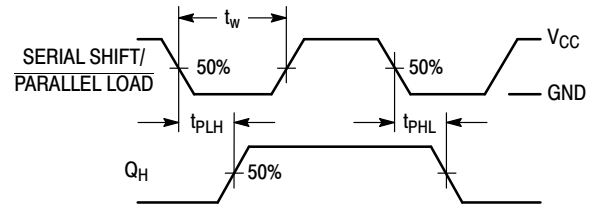


Figure 7.

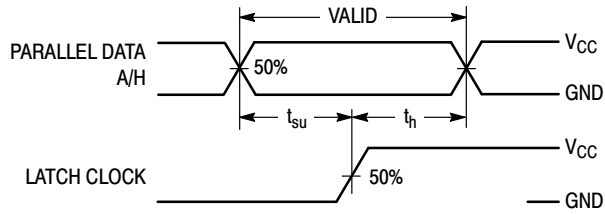


Figure 8.

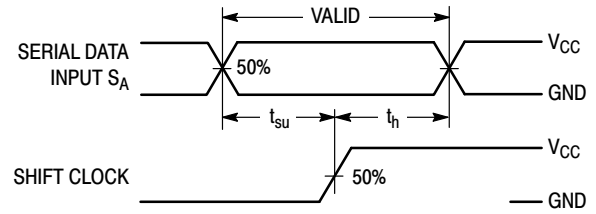


Figure 9.

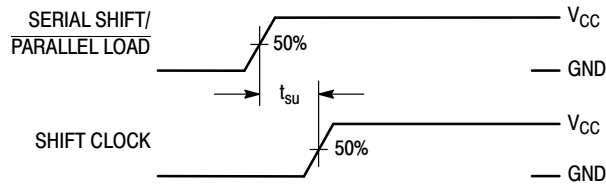


Figure 10.

PIN DESCRIPTIONS

DATA INPUTS

A, B, C, D, E, F, G, H (Pins 15, 1, 2, 3, 4, 5, 6, 7)

Parallel data inputs. Data on these inputs is stored in the input latch on the rising edge of the Latch Clock input.

S_A (Pin 14)

Serial data input. Data on this input is shifted into the shift register on the rising edge of the Shift Clock input if Serial Shift/Parallel Load is high. Data on this input is ignored when Serial Shift/Parallel Load is low.

CONTROL INPUTS

Serial Shift/Parallel Load (Pin 13)

Shift register mode control. When a high level is applied to this pin, the shift register is allowed to serially shift data. When a low level is applied to this pin, the shift register accepts parallel data from the input latch, and serial shifting is inhibited.

Reset (Pin 10)

Asynchronous, Active-low shift register reset. A low level applied to this input resets the shift register to a low level, but does not change the data in the input latch.

Shift Clock (Pin 11)

Serial shift register clock. A low-to-high transition on this input shifts data on the Serial Data Input into the shift register and data in stage H is shifted out Q_H, being replaced by the data previously stored in stage G.

Latch Clock (Pin 12)

Latch clock. A low-to-high transition on this input loads the parallel data on inputs A–H into the input latch.

OUTPUT

Q_H (Pin 9)

Serial data output. This pin is the output from the last stage of the shift register.

EXPANDED LOGIC DIAGRAM



Figure 11. Extended Logic Diagram

MC74HC597A

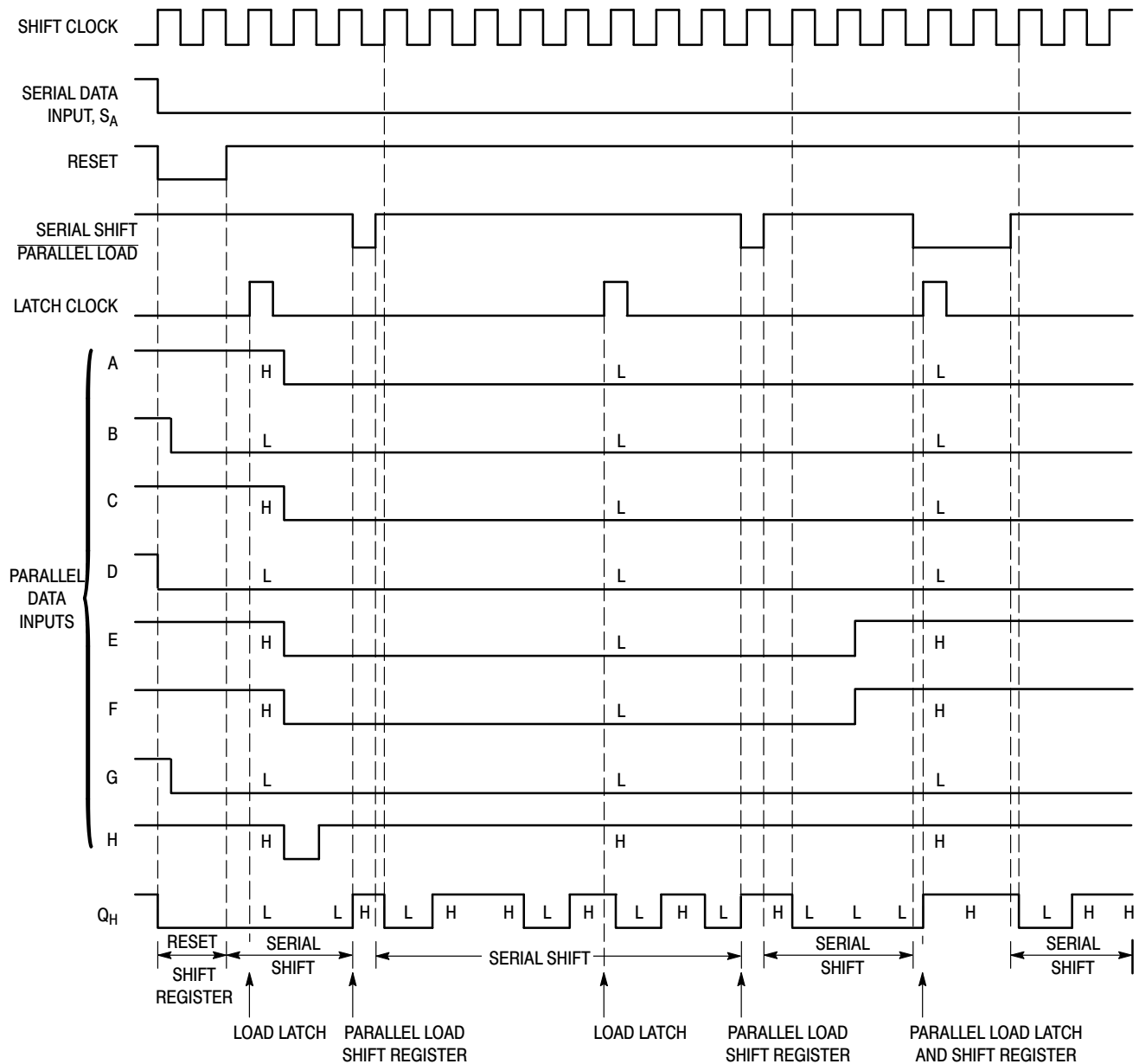


Figure 12. Timing Diagram

ORDERING INFORMATION

Device	Marking	Package	Shipping†
MC74HC597ADG	HC597AG	SOIC-16	48 Units / Rail
MC74HC597ADR2G	HC597AG	SOIC-16	2500 Units / Tape & Reel
MC74HC597ADTR2G	HC 597A	TSSOP-16	2500 Units / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*-Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

MC74HC597A

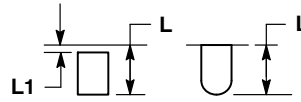
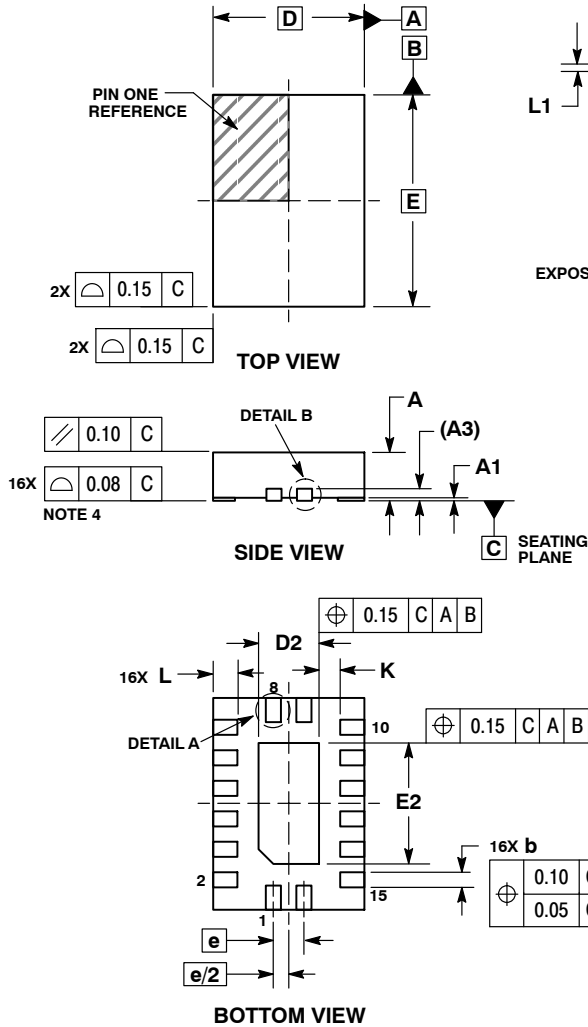
PACKAGE DIMENSIONS



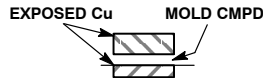
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QFN16, 2.5x3.5, 0.5P
CASE 485AW
ISSUE O

DATE 11 DEC 2008



DETAIL A
ALTERNATE TERMINAL
CONSTRUCTIONS



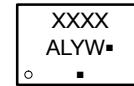
DETAIL B
ALTERNATE
CONSTRUCTIONS

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSIONS b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A3	0.20	REF
b	0.20	0.30
D	2.50	BSC
D2	0.85	1.15
E	3.50	BSC
E2	1.85	2.15
e	0.50	BSC
K	0.20	---
L	0.35	0.45
L1	---	0.15

GENERIC MARKING DIAGRAM*

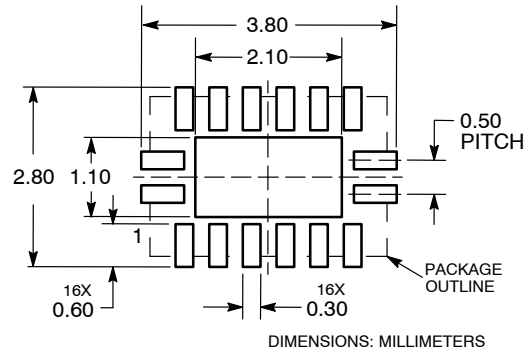


- XXXX = Specific Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
▪ = Pb-Free Package

(Note: Microdot may be in either location)

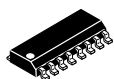
*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

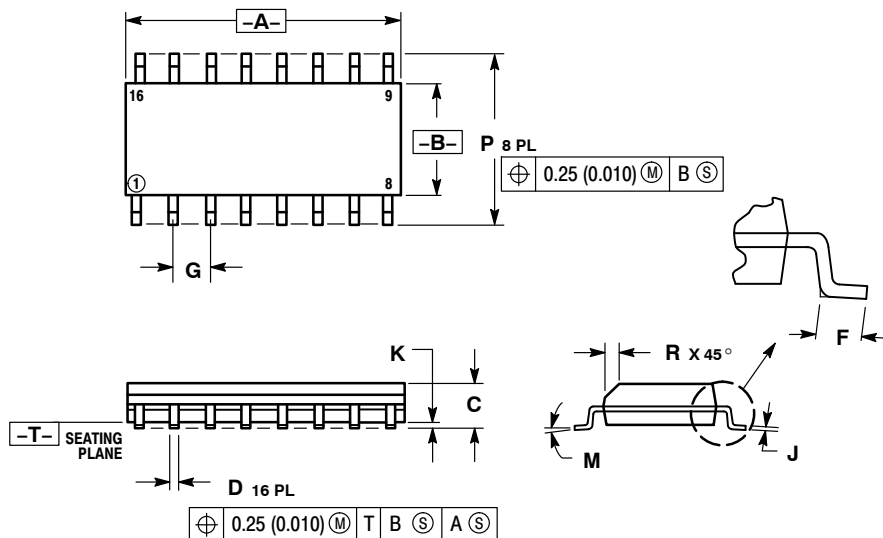
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SCALE 1:1

SOIC-16 CASE 751B-05 ISSUE K

DATE 29 DEC 2006



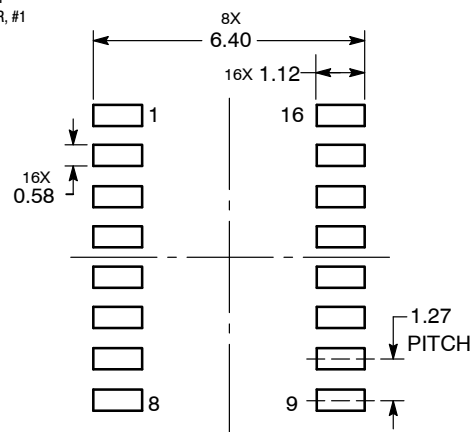
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

STYLE 1: PIN 1. COLLECTOR 2. BASE 3. EMITTER 4. NO CONNECTION 5. EMITTER 6. BASE 7. COLLECTOR 8. COLLECTOR 9. BASE 10. EMITTER 11. NO CONNECTION 12. EMITTER 13. BASE 14. COLLECTOR 15. EMITTER 16. COLLECTOR	STYLE 2: PIN 1. CATHODE 2. ANODE 3. NO CONNECTION 4. CATHODE 5. CATHODE 6. NO CONNECTION 7. ANODE 8. CATHODE 9. CATHODE 10. ANODE 11. NO CONNECTION 12. CATHODE 13. CATHODE 14. NO CONNECTION 15. ANODE 16. CATHODE	STYLE 3: PIN 1. COLLECTOR, DYE #1 2. BASE, #1 3. EMITTER, #1 4. COLLECTOR, #1 5. COLLECTOR, #2 6. BASE, #2 7. EMITTER, #2 8. COLLECTOR, #2 9. COLLECTOR, #3 10. BASE, #3 11. EMITTER, #3 12. COLLECTOR, #3 13. COLLECTOR, #4 14. BASE, #4 15. EMITTER, #4 16. COLLECTOR, #4	STYLE 4: PIN 1. COLLECTOR, DYE #1 2. COLLECTOR, #1 3. COLLECTOR, #2 4. COLLECTOR, #2 5. COLLECTOR, #3 6. COLLECTOR, #3 7. COLLECTOR, #4 8. COLLECTOR, #4 9. BASE, #4 10. EMITTER, #4 11. BASE, #3 12. EMITTER, #3 13. BASE, #2 14. EMITTER, #2 15. BASE, #1 16. EMITTER, #1
STYLE 5: PIN 1. DRAIN, DYE #1 2. DRAIN, #1 3. DRAIN, #2 4. DRAIN, #2 5. DRAIN, #3 6. DRAIN, #3 7. DRAIN, #4 8. DRAIN, #4 9. GATE, #4 10. SOURCE, #4 11. GATE, #3 12. SOURCE, #3 13. GATE, #2 14. SOURCE, #2 15. GATE, #1 16. SOURCE, #1	STYLE 6: PIN 1. CATHODE 2. CATHODE 3. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE 7. CATHODE 8. CATHODE 9. ANODE 10. ANODE 11. ANODE 12. ANODE 13. ANODE 14. ANODE 15. ANODE 16. ANODE	STYLE 7: PIN 1. SOURCE N-CH 2. COMMON DRAIN (OUTPUT) 3. COMMON DRAIN (OUTPUT) 4. GATE P-CH 5. COMMON DRAIN (OUTPUT) 6. COMMON DRAIN (OUTPUT) 7. COMMON DRAIN (OUTPUT) 8. SOURCE P-CH 9. SOURCE P-CH 10. COMMON DRAIN (OUTPUT) 11. COMMON DRAIN (OUTPUT) 12. COMMON DRAIN (OUTPUT) 13. GATE N-CH 14. COMMON DRAIN (OUTPUT) 15. COMMON DRAIN (OUTPUT) 16. SOURCE N-CH	

RECOMMENDED SOLDERING FOOTPRINT*



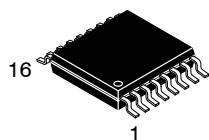
DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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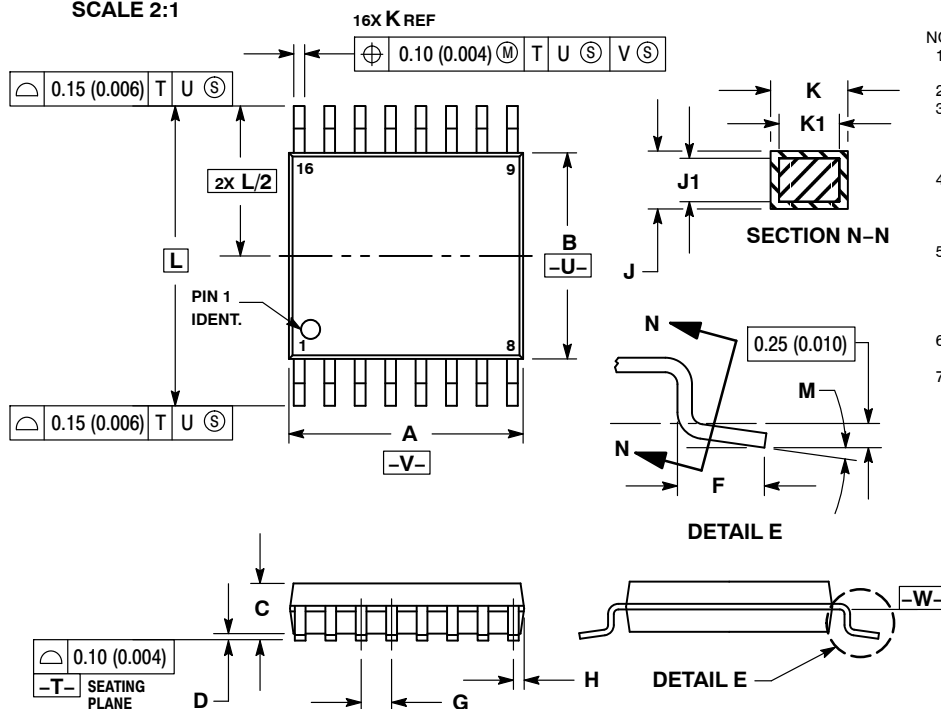
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MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



TSSOP-16 WB
CASE 948F
ISSUE B

DATE 19 OCT 2006

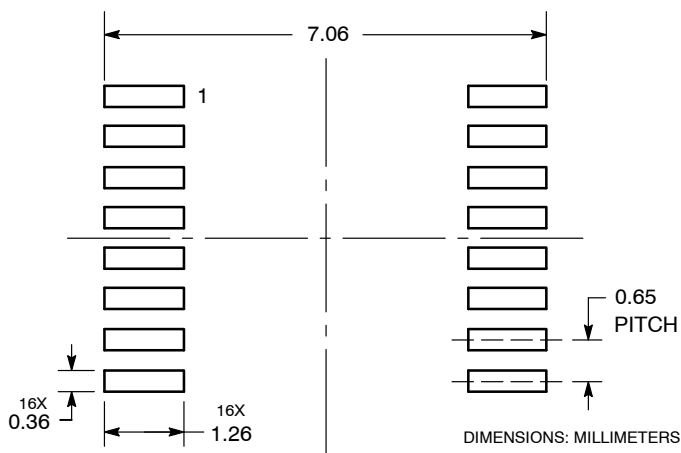


NOTES:

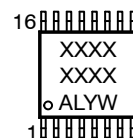
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

RECOMMENDED SOLDERING FOOTPRINT*



GENERIC MARKING DIAGRAM*



- XXXX = Specific Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
G or ■ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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